

WHAT IS CLAIMED IS:

1. A substrate holder for holding a circuit board,
comprising:

5 a main body; and

a holding surface formed on the main body for allowing
a circuit board to adhere to the holding surface,

wherein the holding surface includes:

a first adhesive holding region for holding the circuit
10 board with a first tackiness; and

a second adhesive holding region for holding the circuit
board with a second tackiness which is different from the first
tackiness, such that the first and second adhesive holding regions
hold the circuit board in cooperation.

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2. The substrate holder according to claim 1, further
comprising an adhesive material provided on the main body,

wherein the first adhesive holding region and the second
adhesive holding region are on a surface of the adhesive material.

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3. The substrate holder according to claim 2, wherein
the first adhesive holding region and the second adhesive
holding region are within one area of the adhesive material provided
on the main body.

4. The substrate holder according to claim 2 or 3,
wherein,

the first adhesive holding region and the second adhesive
holding region are composed of the same adhesive material, and

5 the first adhesive holding region and the second adhesive
holding region are imparted with different surface undulation
characteristics.

5. The substrate holder according to claim 4, wherein
10 the first adhesive holding region and the second adhesive
holding region have different surface coarsenesses.

6. The substrate holder according to any of claims 1
to 5, wherein
15 the first adhesive holding region and the second adhesive
holding region are provided within one plane.

7. The substrate holder according to any of claims 1
to 5, wherein
20 the first adhesive holding region and the second adhesive
holding region are differentiated in level.

8. The substrate holder according to claim 7, wherein
one of the first and second adhesive holding regions
25 surrounds the other adhesive holding region, and the other adhesive

holding region projects from the one adhesive holding region.

9. The substrate holder according to claim 7, wherein
a bottom of a depression surrounded by one of the first
5 and second adhesive holding regions comprises the other adhesive
holding region.

10. The substrate holder according to any of claims 1
to 7, wherein,
10 the first tackiness is less than the second tackiness,
and
the second adhesive holding region is confined within
the first adhesive holding region.

15 11. The substrate holder according to any of claims 1
to 10, wherein
the first tackiness is less than the second tackiness,
and
a through hole for receiving a pin is provided in the
20 first adhesive holding region, the pin being used when peeling
off the circuit board.

12. The substrate holder according to claim 11, wherein
an air outlet is provided in the second adhesive holding
25 region.

13. The substrate holder according to any of claims 1
to 7, wherein

the first tackiness is less than the second tackiness,
5 and

the first adhesive holding region is confined within
the second adhesive holding region.

14. The substrate holder according to any of claims 1
10 to 13, wherein

the holding surface includes a plurality of sets of the
first adhesive holding region and the second adhesive holding
region.

15 15. A substrate holder for holding a flexible circuit
board, comprising:

a main body; and

an adhesive material formed on the main body for allowing
a circuit board to adhere to the adhesive material,

20 wherein an undulating pattern for tackiness adjustment
is provided on a surface of the adhesive material.

16. The substrate holder according to claim 2 or 15,
wherein

25 the adhesive material is silicone rubber, polyurethane

rubber, or fluorine rubber.

17. The substrate holder according to any of claims 1 to 16 being used as a pallet for carrying the circuit board.

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18. A method for producing a substrate holder for holding a circuit board, comprising the steps of:

placing an adhesive material on a main body to become the substrate holder; and

10 pressing a mold against the adhesive material while heating the mold, the mold having an undulating pattern for tackiness adjustment provided thereon.

19. The method according to claim 18, wherein
15 the mold includes a region in which a first undulating pattern is formed and a region in which a second undulating pattern is formed.

20. The method according to claim 19, wherein,
20 the mold is differentiated in level between the region in which the first undulating pattern is formed and the region in which the second undulating pattern is formed.

21. A method for producing a mold to be used for forming
25 an undulating pattern for tackiness adjustment on an adhesive

material of a substrate holder for holding a circuit board,
comprising the steps of:

forming a pressing surface of the mold; and
blasting minute particles against the pressing surface.

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22. The method according to claim 21, further comprising,
before the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing
surface.

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23. The method according to claim 21 or 22, further
comprising, after the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing
surface; and

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blasting another type of minute particles against the
pressing surface through the mask.

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24. A method for producing a mold to be used for forming
an undulating pattern for tackiness adjustment on an adhesive
material of a substrate holder for holding a circuit board,
comprising the steps of:

forming a pressing surface of the mold; and

forming an undulating pattern on the pressing surface
by chemical etching.